

Filename: PMP7047REVC_BILLOFMATERIALS_bom.xls						
Date: 01/25/2012						
PMP7047REVC_BILLOFMATERIALS BOM						
COUNT	RefDes	Value	Description	Size	Part Number	MFR
6	C101-103 C106-108	22uF	Capacitor, Ceramic, 25V, X5R, 20%	1210	GRM32ER71E226KE15L	Murata
2	C104 C110	150u	Capacitor, OSCON, 20V, 20milliohm, 20%	10.3mm (F12)	20SVP150M	Sanyo
2	C105 C118	1uF	Capacitor, Ceramic, 25V, X7R, 20%	0805	Std	Std
1	C111	1.0uF	Capacitor, Ceramic, 25V, X5R, 20%	0805	Std	Std
1	C112	4.7uF	Capacitor, Ceramic, 10V, X5R, 20%	0805	Std	Std
1	C113	150nF	Capacitor, Ceramic, 16V, X7R, 20%	0402	Std	Std
2	C114 C199	100nF	Capacitor, Ceramic, 16V, X7R, 20%	0402	Std	Std
1	C115	150nF	Capacitor, Ceramic, 25V, X7R, 10%	0402	Std	Std
1	C116	1500pF	Capacitor, Ceramic, 25V, C0G, 10%	0402	Std	Std
1	C117	22nF	Capacitor, Ceramic, 25V, C0G, 10%	0402	Std	Std
6	C119-124	470u	Capacitor, Polymer Alum., 2V, 3milliOhm	7343	EEFGX0D471R	Panasonic
1	C198	3.9nF	Capacitor, Ceramic, 50V, X5R, 20%	0805	Std	Std
1	D199	BZX84C3V3	Diode, Zener, 3.3-V, 350-mW	SOT-23	BZX84C3V3	Diodes
2	J101-102	ED120/4DS	Terminal Block, 4-pin, 15-A, 5.1mm	0.80 x 0.35 inch	ED120/4DS	OST
1	J198	PEC06SAAN	Header, Male 6-pin, 100mil spacing,	0.100 inch x 6		Sullins
1	J199	PEC02SAAN	Header, Male 2-pin, 100mil spacing,	0.100 inch x 2		Sullins
1	L101A199	600nH	Inductor, SMT, 41Arms-A, 0.74-milliohm	0.790 x 0.770 inch	SER2009-601MX	Coilcraft
1	L101B199	500nH	Inductor, SMT, 27Arms-A, 0.87-milliohm	0.620 X 0.640 inch	SER1590-501MX	Coilcraft
1	L101C199	440nH	Inductor, SMT, 30A	0.530 x 0.510 inch	PA0513-441NLT	Pulse
1	R101	2.49k	Resistor, Chip, 1/16W, 1%	0402	Std	Std
1	R102	5.1	Resistor, Chip, 1/16W, 1%	0402	Std	Std
1	R103	1.2k	Resistor, Chip, 1/16W, 1%	0402	Std	Std
2	R104 R107	13.7k	Resistor, Chip, 1/16W, 1%	0402	Std	Std
1	R105	49.9	Resistor, Chip, 1/16W, 5%	0402	Std	Std
1	R106	68	Resistor, Chip, 1/16W, 1%	0402	Std	Std
1	R192	100k	Resistor, Chip, 1/16W, 1%	0603	Std	Vishay
2	R193-194	1.5	Resistor, Chip, 0.6W, 1%	2010	Std	STD
1	R195	10	Resistor, Chip, 1/16W, 1%	0402	Std	Std
1	R196	40.2k	Resistor, Chip, 1/16W, 1%	0402	Std	Std
1	R197	10k	Resistor, Chip, 1/16W, 1%	0402	Std	Std
2	R198-199	13.3k	Resistor, Chip, 1/16W, 1%	0402	Std	Std
2	TP101 TP103	5010	Test Point, Red, Thru Hole	0.125 x 0.125 inch	5010	Keystone

3	TP102 TP104 TP109	5011	Test Point, Black, Thru Hole	0.125 x 0.125 inch	5011	Keystone
2	TP105-106	5014	Test Point, Yellow, Thru Hole	0.125 x 0.125 inch	5014	Keystone
2	TP107-108	5012	Test Point, White, Thru Hole	0.125 x 0.125 inch	5012	Keystone
1	U101	TPS56221DQP	IC, 25A 600kHz Synchronous BUCK Converter	QFN-22 6X5 mm	TPS56221DQP	TI
1	U199	LM10010SD	IC, VID Voltage Programmer for Point of Load Regulator	LLP-10	LM10010SD	TI
Notes:	1. These assemblies are ESD sensitive, ESD precautions shall be observed.					
	2. These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.					
	3. These assemblies must comply with workmanship standards IPC-A-610 Class 2.					
	4. Ref designators marked with an asterisk (***) cannot be substituted.					
	All other components can be substituted with equivalent MFG's components.					

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